

Product / Process Change Notification



N° 2014-107-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Infineon goes Green:

Implementation of a Green version (RoHS compliant) for TLE4205G and change from Gold to Copper Wire

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **11. May 2015**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response by the date in the PCN above we consider this as the acceptance of the PCN. After the last order date as stated herein, purchase orders related to the unchanged product(s) cannot be accepted.

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SUBJECT OF CHANGE: Implementation of a Green version (RoHS compliant) for TLE4205G and introduction of copper (Cu) instead of gold (Au) as bond wire material

PRODUCTS AFFECTED:	Type	SP n°	OPN	Package
	TLE4205G	SP000011747	TLE4205GNTMA1	P-DSO-20-17

REASON OF CHANGE: **New environmentally friendly materials will be introduced** to meet customer requirements and the demands of the European Union Directive on the Restriction of the use of Hazardous Substances (**RoHS**) and the Directives of Waste Electrical and Electronic Equipment (**WEEE**).
Copper bond wires show superior electrical and mechanical properties and a well formed, even more stable inter-metallic copper-aluminum phase compared to conventional gold bond wires on aluminum (Al) bond pads.

DESCRIPTION OF CHANGE:	<u>OLD</u>	<u>NEW</u>
■ Wafer technology	Standard passivation	Robust passivation
■ Wire Bond	30µm Gold	30µm Copper
■ Plating lead surface	SnPb	Sn
■ Package	Standard grey	Robust green
■ Moisture Level	MSL1 @ 220°C	MSL3 @ 260°C

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- PRODUCT IDENTIFICATION:**
- On Packing Level:
 - "PB" logo is either printed on the Barcode product label or as a sticker on the product packing
 - Package name will change for grey products from P-DSO/P-TO to PG-DSO/PG-TO with the "G" indicating that the product is green
 - On Product Level:
 - "G" in front of the date code
 - New SP-Number
 - On Datasheet level:
 - New data sheet: Rev. 1.1
 - RoHS logo on datasheet
 - Package name will change for grey products from P-DSO to PG-DSO with the "G" indicating that the product is green

TIME SCHEDULE:

■ Final qualification report:	available
■ First samples available:	available
■ Start of delivery:	30-Sep-2015 or earlier after customer release
■ Last order date of unchanged product:	30-Sep-2015
■ Last delivery date of unchanged product:	30-Mar-2016

ASSESSMENT:

No impact on reliability proven via technology and product qualification. Processes are optimized to meet product performance according to specification.
No change in form and fit

DOCUMENTATION:

3_cip14107	replacement table
4_cip14107	data sheet

PRODUCT REPLACEMENT



referring to PCN N° 2014-107-A

■ Last order date of unchanged product:	2015-09-30
■ Last delivery date of unchanged product	2016-03-30

OLD (TO BE REPLACED)				NEW (REPLACEMENT)		
Device	SP N°	OPN	Package	Device	SP N°	Package
TLE4205G	SP000011747	TLE4205GNTMA1	P-DSO-20-17	TLE4205G	SP001130456	PG-DSO-20-66

If you have any questions, please do not hesitate to contact your local Sales office.